NXP

Final Product Change Notification	201109002F01U01

Issue Date: 23-Jul-2013
Effective Date: 21-Oct-2013   **UPDATE**

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For detailed information we invite you to view this notification online

QUALITY

Management Summary

Change from 4 inch to 6 inch MR wafer fab process at DHAM.

Change Category

Wafer Fab process	Assembly Process	Product Marking	Design
Wafer Fab materials	Assembly Materials	Electrical spec./Test coverage	Mechanical Specification
Wafer Fab location	Assembly Location	Test Location	Packing/Shipping/Labeling

6 inch LAM AL Process Transfer for Wheelspeedsensor OH1xx Types

Details of this Change

- MR wafer process move from 4 inch to 6 inch
- Use of 6 inch LAM etching process
- Use of 6 inch stepper lithography instead of 4 inch contact lithography
- Use of state of the art PAS-stepper lithography instead of older Utratech-stepper for ASIC

Why do we Implement this Change

- Improving quality and safeguarding supplies in future
- Capacity limitation / discontinuation 4 inch fab for MR
- Process improvment by state of art lithography
- Standardization of equipment
- Improvement of product characteristics

Identification of Affected Products

By lot, date code and customer information on packing labels

Product Availability

Sample Information
Samples are available upon request

Production
Planned first shipment 01-Sep-2013

Update Information

update of productlist with new product names and new 12NC

Impact

no impact to the product's functionality anticipated.

Data Sheet Revision
No impact to existing datasheet

Disposition of Old Products
Existing inventory will be shipped until depleted

Timing and Logistics

Your acknowledgement of this change, conform JEDEC JESD46 D, is expected till 22-Aug-2013.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:
Name   Ingobert Gorlt
Position   Customer Quality Manager
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At NXP Semiconductors we are constantly striving to improve our product and processes to ensure they reach the highest possible Quality Standards.
Customer Focus, Passion to Win.

NXP Quality Management Team.

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A global semiconductor company with operations in more than 25 countries, NXP posted unaudited revenue of $4.36 billion in 2012.

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